



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of: **Mami NAKADATE et al.**

Group Art Unit: **Unassigned**

Serial Number: **10/769,747**

Examiner: **Unassigned**

Filed: **February 3, 2004**

For: **SOLDER JOINT LIFE PREDICTION METHOD**

Attorney Docket No.: **042072**

Customer No.: 38834

**INFORMATION DISCLOSURE STATEMENT**  
**PURSUANT TO 37 CFR 1.97(b)**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, Virginia 22313-1450

March 25, 2004

Sir:

Applicants direct the attention of the Patent and Trademark Office to the documents listed on the attached Form PTO-1449. A copy of each listed document is attached.

No fee or certification is required in connection with this Information Disclosure Statement, because it is being submitted prior to the issuance of a first official action on the merits or expiration of the three month period following the filing date or the entry of the national stage of the above-captioned application.

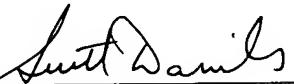
The above information is presented so that the Patent and Trademark Office can, in the first instance, determine any materiality thereof to the claimed invention. Applicants respectfully request that the information be expressly considered during the prosecution of this application and that the documents cited in the attached Form PTO-1449 be made of record therein and appear on the first page of any patent to issue therefrom.

Information Disclosure Statement dated March 25, 2004  
Application Serial No. 10/769,747  
Attorney Docket No.: 042072

The Commissioner is authorized to charge our Deposit Account No. 50-2866 for any fee that is required to effect consideration of this statement.

Respectfully submitted,

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Attachments: PTO Form 1449 w/8 references  
SMD/rer



**INFORMATION  
DISCLOSURE  
CITATION  
PTO-1449**

Atty. Docket No. 042072 Serial No. 10/769,747

Applicant(s): Mami NAKADATE et al.

Filing Date: February 3, 2004 Group Art Unit: Unassigned

**FOREIGN PATENT DOCUMENTS**

		Document No.	Date	Country	Translation (Yes or No)
	AA	56-148068	11/17/81	Japan	Abstract
	AB	04-083343	3/17/92	Japan	Abstract
	AC	2001-060605	3/6/01	Japan	Abstract

**OTHER DOCUMENTS**

_____	AD	Research Report RC162, Special Interest Group on Reliability Assessment for Electronics Packaging, Chapter 20, May 11, 2000 (whole translation)
_____	AE	7 <sup>th</sup> Symposium on Microjoining and Assembly Technology in Electronics, 2001, pp. 35-40 (whole translation)
_____	AF	7 <sup>th</sup> Symposium on Microjoining and Assembly Technology in Electronics, 2001, pp. 41-46 (whole translation)
_____	AG	Analysis of Phase Growth Process in SN/PB Eutectic Solder Joint, EEP-Vol. 26-1, Advance in Electronic Packaging; Editors: D. Agonafter, M. Saka, and Y.C. Lee Bok. No. G1107A-1999
_____	AH	A Microstructural Evaluation Method of Thermal Fatigue Crack Initiation in SN/PB Eutectic Solder Joints, IPACK2001-15572, Proceedings of IPACK'01, The Pacific Rim/ASME International Electronic Packaging Technical Conference and Exhibition, July 8-13, 2001, Kauai, Hawaii, USA

Examiner

Date Considered